IPC ASSOCIATION CONNECTED ELECTRONICS INDUST	© Copyright 2005, IPC.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowel level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typhttp://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater						als and Mf	g Inforr	mation		
Supplier Info	rmation				•											
Company name* Comp				Company unique ID			Unique ID Authority					Response Date*				
nsemi												2023-06-08				
Contact Name		Title - Contact			P	Phone - Contact*					Email - Contact*					
Product-Env-Ste	ewards	Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com						
Authorized Representative* Titl				Title - Representative			Phone - Representative*				Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com					
Reque	ester Item Number	Mfr Item	m Number Mfr Item Name				Effective Dat	te Versi	Version Ma		Manufacturing Site		eight*	UON	М	Unit Type
		NCV8752BMX28TCG 200 mA LDO, Noise, PG del		200 mA LDO, UI Noise, PG delay 2		IQ, Ultra-Low 2023-0		MY1			3.64		mg		Each	
Ianufacturin	ng Proccess Information	n														
Termin	nal Plating / Grid Array Materi	al T	Terminal Base Alloy J		J-STD-020 MSL	TD-020 MSL Rating		Peak Process Body Temperatur		re Max Time at Peak Temper		Temperatu	rature Number of Reflow Cycles		S	
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		u) (no C	CU Alloy 1		1		260		С		30 seco		s 3			
comments																
vel 1 - maximun	n time at peak temperature	during sol	dering is 10-30	0 seconds								<u> </u>				
or more informa	ation regarding material con	nposition	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier has not a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.25	mg	Supplier	Silicon (Si)	7440-21-3		0.25	mg
Die Attach	0.18	mg	Supplier	Epoxized Condensate Of Para- Hydrobenzaldehyde And Alkyl Phenol	129915-35-1		0.108	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.072	mg
Lead Frame	1.9	mg	Supplier	Tin (Sn)	7440-31-5		0.0047	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0042	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0047	mg
			Supplier	Copper (Cu)	7440-50-8		1.8863	mg
Mold Compound-Black	1.27	mg		Epoxy resin	proprietary data		0.0889	mg
			Supplier	Phenolic Resin	Proprietary Data		0.0889	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.1905	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0063	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		0.8953	mg
Plating	0.03	mg	Supplier	Palladium (Pd)	7440-05-3		0.0007	mg
			В	Nickel (Ni)	7440-02-0		0.0264	mg
			Supplier	Gold (Au)	7440-57-5		0.0028	mg
Wire Bond - Au	0.01	mg	Supplier	Gold (Au)	7440-57-5		0.01	mg